# 504278762 03/19/2017

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2

1 EPAS ID: PAT4325444

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date		
FU-HSUAN CHU	03/10/2017		
HUA-WEI PENG	03/10/2017		

#### **RECEIVING PARTY DATA**

Name:	UNITED MICROELECTRONICS CORP.		
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park		
City:	Hsin-Chu City		
State/Country:	TAIWAN		

### **PROPERTY NUMBERS Total: 1**

Property Type	Number			
Application Number:	15401087			

#### **CORRESPONDENCE DATA**

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NAME OF SUBMITTER:	SIBYL YU
SIGNATURE:	/SIBYL YU/
DATE SIGNED:	03/19/2017

#### **Total Attachments: 4**

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PATENT 504278762 REEL: 041628 FRAME: 0080

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

# Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I here This declaration is directed to:	by deck	are that:					
☐ The attached application, or		3					
☑ United States application nu	mber	15/401,087		filed on 0	1/08/201	7	or
☐ PCT international application	numl	ber		filed on			
The above-identified application was	made (	or authorized to b	oe made b	y me.			
I believe that I am the original invento application.	or or an	original joint inve	entor of a	claimed inve	ention in th	he	
l hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false s sonmei	tatement made in nt of not more tha	n this deck an five (5)	aration is pu years, or bo	nishable th.		
In consideration of the payment by	UNITE CORF	ED MICROELE ?.	CTRON	ICS hav	ing a post	al add	ress of
No.3, Li-Hsin Road 2, Science	-Base	d Industrial Pa	ark, Hsin	 n-Chu City	300, Ta	iwan	, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an	I of the	e sum of One Dol ble consideration	llar (\$ 1.00 1.	)), the receip	ot of which	n is he	reby
hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified applicat invention by the above application or substitutes, or extensions thereof, an	d to an ion and any co	y and all improve i, in and to, all Le ntinuations, conti	ements wh etters Pate inuation-in	ich are disc nt to be obta -part, divisio	osed in thained for sons, renev	ne said vals.	EE
hereby covenant that no assignmen entered into which would conflict with	t, sale, this as	agreement or en signment;	cumbranc	e has been	or will be	made	or
further covenant that ASSIGNEE wi and documents relating to said inven known and accessible to I and will te related thereto and will promptly exec	tion and stify as	d said Letters Pal to the same in ar	tent and le ny interfera	gal equivalence. Iitigatio	ents as ma	av be	ts
representatives any and all papers, in maintain, issue and enforce said app equivalents thereof which may be nea N WINTNESS WHEREOF, I have he	lication, cessary	, said invention a or desirable to d	nd said Le carry out th	tters Patent	and said thereof.	Date o	f signing)
Note: An application data sheet (PTC nventive entity, must accompany this	)/SB/14 form. (	or equivalent), ir Use this form for	ncluding na each addi	aming the e tional invent	ntire or.		

NPO#NAU-P2921-USA:0 CUST#UMCD-2016-0704 Page 1 of 4

F#NPO-P0002E-US1201 DSB0-106U006233

PATENT REEL: 041628 FRAME: 0081

### Docket No NAUP2921USA

LEGAL NAME OF INVENTOR(ASSIGNOR)						
Inventor:	Fu-Hsuan Chu	Date;	MAR	1	0	2017

Signature: Fu-Hsuan Chu

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NPO#NAU-P2921-USA:0 CUST#UMCD-2016-0704 F#NPO-P0002E-US1201 DSB0-106U006233

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

Title of Invention: SEMICONDUCTOR STRUCTURE

As the below named inventor, I hereby declare that: This declaration is directed to:	
☐ The attached application, or	
☑ United States application number 15/401,087 filed on 01/08/2017 , o	or
☐ PCT international application number filed on	
The above-identified application was made or authorized to be made by me.	
I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.	
I hereby acknowledge that any willful false statement made in this declaration is punishable under18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.	
In consideration of the payment by UNITED MICROELECTRONICS having a postal addre	ss of
No.3, Li-Hsin Road 2, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, F	R.O.C.
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is herel acknowledged, andfor other good and valuable consideration.	Эу
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.	=
l hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;	
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal	
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.  IN WINTNESS WHEREOF, I have hereunto set hand and seal this	igning)
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>	

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NPO#NAU-P2921-USA:0 CUST#UMCD-2016-0704

F#NPO-P0002E-US1201 DSB0-106U006233

# Docket No NAUP2921USA

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Hua-Wei Peng	Date:	MAR 1 0 2017	
Signature;	Hua-Wei Peng			
	V .			

NPO#NAU-P2921-USA:0 CUST#UMCD-2016-0704 Page 4 of 4

F#NPO-P0002E-US1201 DSB0-106U006233

PATENT REEL: 041628 FRAME: 0084